

SMD METALLIZED FILM-OVER-FOAM GROUNDING CONTACT

Laird's SMD (Surface Mount Device) Grounding Contact is a foam cored contact with a metallized polyimide film outer covering. It is used for circuit grounding of SMT (Surface Mount Technology) devices. These contacts are designed to be solder reflow compatible, and are suitable for automatic processing.

FEATURES

- Sn/Cu Plated PI Film outer layer
- Polymeric Foam Core
- Soft SMD contacts are RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Reflow tunnel compatible to 260° C
- Patent Pending
- UL94 V0 Flammability Rating (Pending)

MARKETS

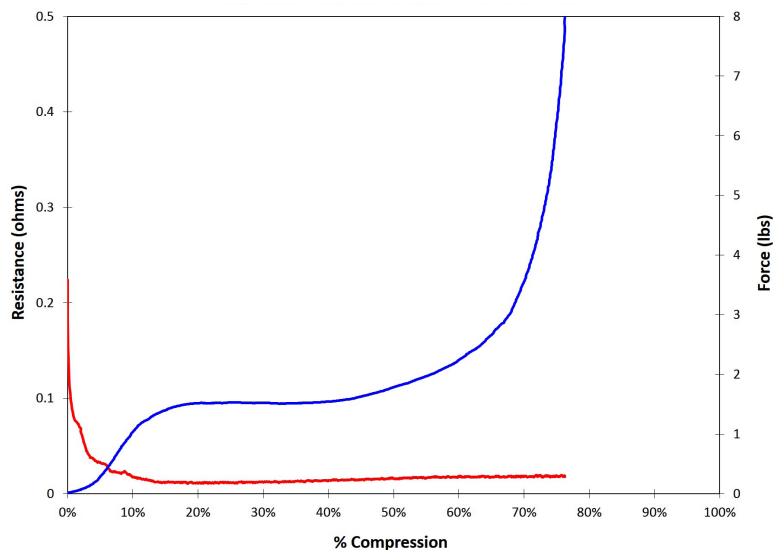


- Cabinet applications
- LCD and Plasma TV
- Medical equipment
- Servers
- Printers
- Automotive
- Laptop computers and tablets
- Networking equipment
- Desktop computers
- Telecommunications cabinets

Item	Unit	Value	Test Method
Z-Axis Resistance			Laird Internal
Before Reflow	Ω	<0.06	
After Reflow	Ω	<0.10	
Flammability		Pending	UL 94 V0*
Solder Adhesion Strength (Contact to PCB)	kgf	>0.8	Laird Internal
Hardness (Shore A)	durometer	<20	ASTM D 2240
Compression Set	%	<20	ASTM D3574 Test D
Recommended Compression	%	15 to 30	
Operation Temperature	°C	-40° to 85°	
Restricted Substances		RoHS Compliant Halogen Free	

* UL file number E170327, UL designation code V0 050 (Pending)

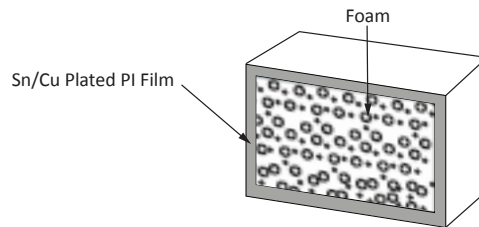
Force/Displacement/Graph of
5mm x 5mm x 5mm Soft FR SMD



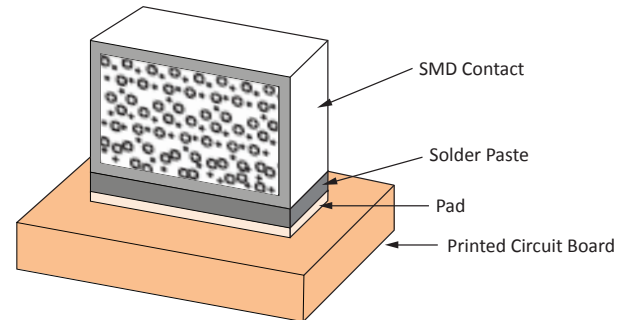
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Soft FR SMD Grounding Contacts Metallized Film-over-Foam

PRODUCT COMPOSITION

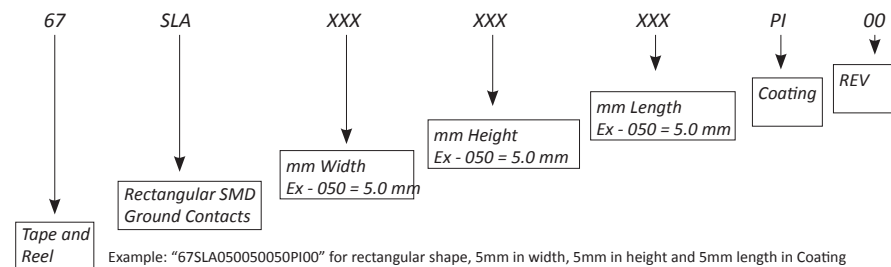
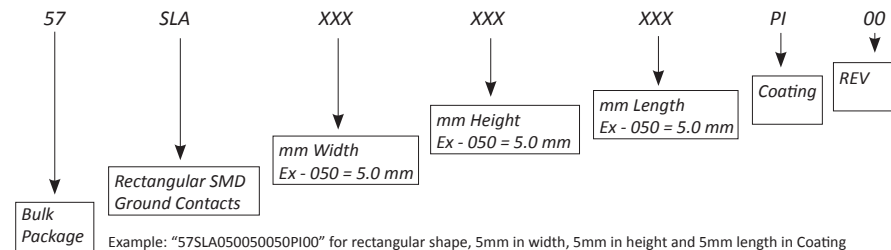


PRODUCT APPLICATION



EX: 57SLA050050050PI00	57 (Bulk pkg)	SLA Rectangle	XXX (mm Width) Ex. 050 = 5.0mm	XXX (mm Height) Ex. 050 = 5.0mm	XXX (mm Length) Ex. 050 = 5.0mm	PI Coating PI	00 REV
EX: 67SLA050050050PI00	67 (Tape & Reel)	SLA Rectangle	XXX (mm Width) Ex. 050 = 5.0mm	XXX (mm Height) Ex. 050 = 5.0mm	XXX (mm Length) Ex. 050 = 5.0mm	PI Coating PI	00 REV

PART NUMBER STRUCTURE



TYPICAL REFLOW CONDITIONS

	Temperature Profile	Condition	
		Temperature	Time
A	Preheating Stage	Room Temp. -170°C	125 sec.
B	Heating / Soaking Stage	170-217°C	100 sec.
C	Reflow Stage	217-Peak Temp.(~260°C Max)	50 sec.
D	Cooling Stage	Peak Temp. - Room Temp.	>60 sec.

Product is available in tape and reel packaging

Values presented have been determined by standard test methods and are typical values not to be used for specification purposes.

EMI-DS-FOF-SOFT-FR-SMD 070215

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